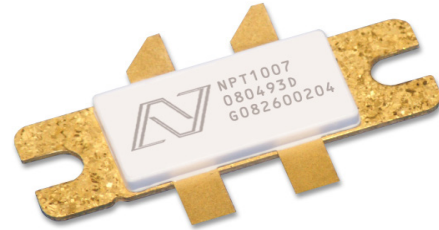


Gallium Nitride 28V, 200W RF Power Transistor

Built using the SIGANTIC® NRF1 process - A proprietary GaN-on-Silicon technology

FEATURES

- Optimized for narrowband and broadband applications from DC – 1200MHz
- 200W P_{3dB} CW power at 900MHz in quadrature combined or push-pull configuration
- 90W CW power from 500-1000MHz in application design [AD-014](#)
- High efficiency from 14V to 28V
- 1.0 °C/W R_{TH} with maximum T_J rating of 200°C
- Robust up to 10:1 VSWR mismatch at all angles with no device degradation
- Subject to EAR99 export control



DC – 1200 MHz
14 – 28 Volt
GaN HEMT



RF Specifications (CW): V_{DS} = 28V, I_{DQ} = 1400mA¹, Frequency = 900MHz, T_A = 25°C, Measured in Nitronex Quadrature Combined Test Fixture².

| Symbol | Parameter | Min | Typ | Max | Units |
|------------------|---|---------------------------------|------|-----|-------|
| P _{3dB} | Average Output Power at 3dB Gain Compression | 52.0 | 53.0 | - | dBm |
| G _{SS} | Small Signal Gain | 17.3 | 18.3 | - | dB |
| η | Drain Efficiency at 3dB Gain Compression ² | 57 | 63 | - | % |
| VSWR | 10:1 VSWR at all phase angles | No change in device performance | | | |

Note 1: 700mA per transistor. Each gate should be biased independently to set desired I_{DQ}.

Note 2: Includes ~ 0.2 dB quadrature combiner loss.

Typical 2-Tone Performance: V_{DS} = 28V, I_{DQ} = 1400mA¹, Frequency = 900MHz, Tone spacing = 1MHz, T_A = 25°C Measured in Nitronex Quadrature Combined Test Fixture².

| Symbol | Parameter | Typ | Units |
|----------------------|---|------|-------|
| P _{3dB,PEP} | Peak Envelope Power at 3dB Gain Compression | 53.4 | dBm |
| P _{1dB,PEP} | Peak Envelope Power at 1dB Gain Compression | 52.6 | dBm |
| P _{IMD3} | Peak Envelope Power at -35dBc IMD3 | 50.8 | dBm |

Note 1: 700mA per transistor. Each gate should be biased independently to set desired I_{DQ}.

Note 2: Includes ~ 0.2 dB quadrature combiner loss.

DC Specifications: Per Transistor, $T_A = 25^\circ\text{C}$

| Symbol | Parameter | Min | Typ | Max | Units |
|----------------------------|--|------|------|------|----------|
| Off Characteristics | | | | | |
| V_{BDS} | Drain-Source Breakdown Voltage ($V_{GS} = -8\text{V}$, $I_D = 36\text{mA}$) | 100 | - | - | V |
| I_{DLK} | Drain-Source Leakage Current ($V_{GS} = -8\text{V}$, $V_{DS} = 60\text{V}$) | - | 9 | 18 | mA |
| On Characteristics | | | | | |
| V_T | Gate Threshold Voltage ($V_{DS} = 28\text{V}$, $I_D = 36\text{mA}$) | -2.3 | -1.8 | -1.3 | V |
| V_{GSQ} | Gate Quiescent Voltage ($V_{DS} = 28\text{V}$, $I_D = 700\text{mA}$) | -2.0 | -1.5 | -1.0 | V |
| R_{ON} | On Resistance ($V_{GS} = 2\text{V}$, $I_D = 270\text{mA}$) | - | 0.13 | 0.14 | Ω |
| $I_{D,MAX}$ | Drain Current ($V_{DS} = 7\text{V}$ pulsed, 300 μs pulse width, 0.2% duty cycle) | 19.0 | 20.5 | - | A |

Absolute Maximum Ratings: Not Simultaneous, Per Transistor, $T_A = 25^\circ\text{C}$ Unless Otherwise Noted

| Symbol | Parameter | Max | Units |
|---------------|--|-------------|---------------------------|
| V_{DS} | Drain-Source Voltage | 100 | V |
| V_{GS} | Gate-Source Voltage | -10 to 3 | V |
| I_G | Gate Current | 180 | mA |
| P_T | Total Device Power Dissipation (Derated above 25°C), both transistors on | 175 | W |
| θ_{JC} | Thermal Resistance (Junction-to-Case), composite for both transistors on, $T_J = 180^\circ\text{C}$ | 1.0 | $^\circ\text{C}/\text{W}$ |
| | Thermal Resistance (Junction-to-Case), one transistor on, one off, $T_J = 180^\circ\text{C}$ | 1.8 | |
| T_{STG} | Storage Temperature Range | -65 to 150 | $^\circ\text{C}$ |
| T_J | Operating Junction Temperature | 200 | $^\circ\text{C}$ |
| HBM | Human Body Model ESD Rating (per JESD22-A114) | 1C (>1000V) | |
| MM | Machine Model ESD Rating (per JESD22-A115) | A (>100V) | |
| CDM | Charge Device Model ESD Rating (per JESD22-C101) | IV (>4000V) | |

Load-Pull Data, Reference Plane at Device Leads

$V_{DS}=28V$, $I_{DQ}=700mA$, One Single-Ended Transistor, $T_A=25^\circ C$ Unless Otherwise Noted

Table 1: Optimum Source and Load Impedances for CW Gain, Drain Efficiency, and Output Power Performance

| Frequency (MHz) | $Z_S (\Omega)$ | $Z_L (\Omega)$ | P_{SAT} (dBm) | G_{SS} (dB) | Drain Efficiency @ P_{SAT} (%) |
|-----------------|----------------|----------------|-----------------|---------------|----------------------------------|
| 500 | $1.4 + j0.1$ | $2.0 + j0.5$ | 50.0 | 24.0 | 70% |
| 900 | $1.6 - j1.5$ | $2.3 - j1.5$ | 50.0 | 18.5 | 74% |
| 1200 | $1.8 - j2.7$ | $3.5 - j2.8$ | 49.5 | 16.5 | 62% |

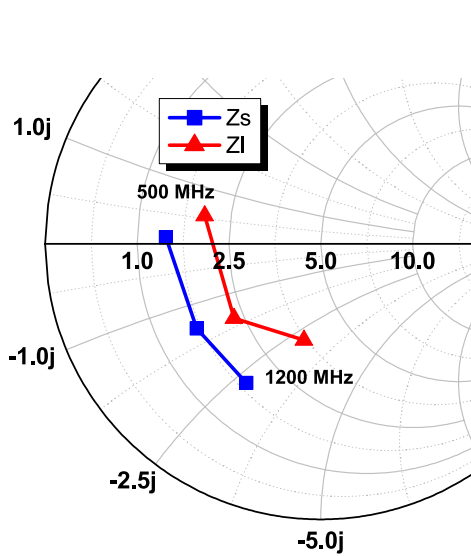
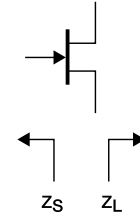


Figure 1 - Optimum Impedances for CW Performance

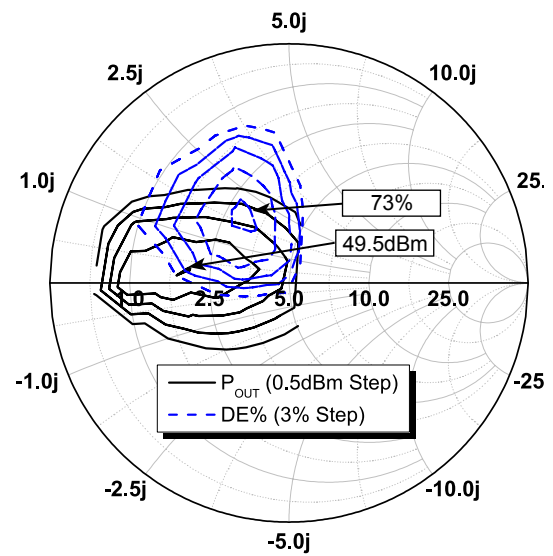


Figure 2 - Load-Pull Contours, 500MHz, $P_{IN} = 25dBm$, $Z_S = 1.4 + j0.1 \Omega$

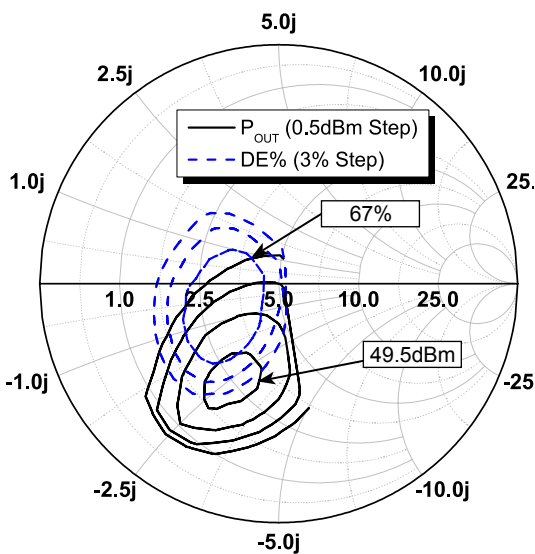


Figure 3 - Load-Pull Contours, 900MHz, $P_{IN} = 30dBm$, $Z_S = 1.6 - j1.5 \Omega$

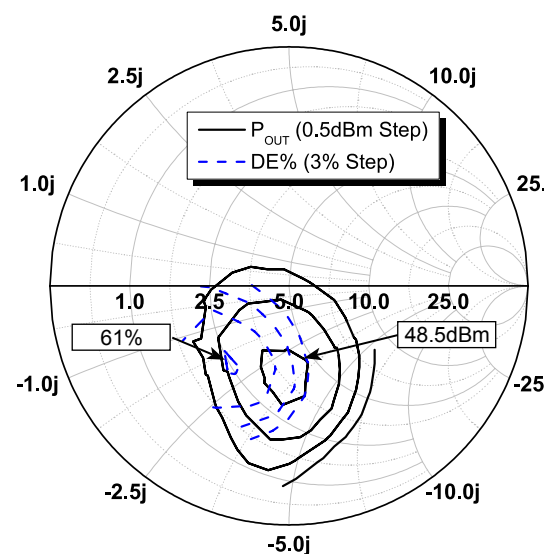


Figure 4 - Load-Pull Contours, 1200MHz, $P_{IN} = 32dBm$, $Z_S = 1.8 - j2.7 \Omega$

Load-Pull Data per Device Lead, Reference Plane at Device Leads

$V_{DS}=28V$, $I_{DQ}=700mA$, One Single-Ended Transistor, $T_A=25^{\circ}C$ unless otherwise noted.

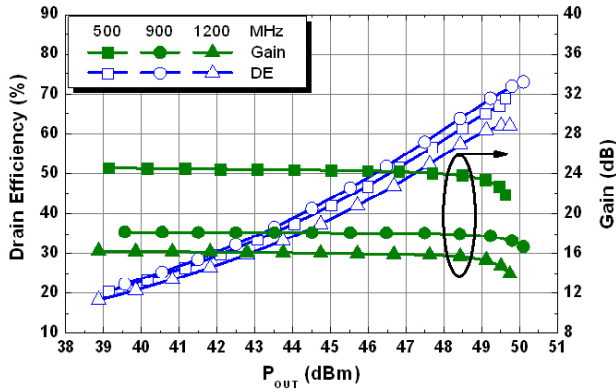


Figure 5 - Typical CW Performance, over Frequency

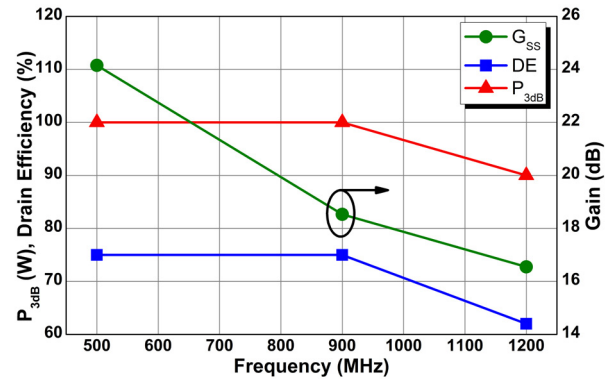


Figure 6 - Typical CW Performance over Frequency

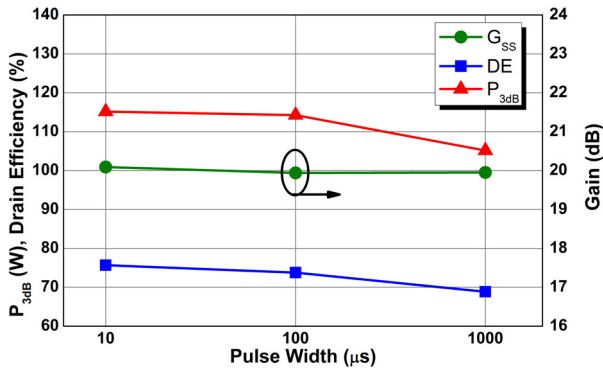


Figure 7 - Typical Pulsed Performance, Frequency = 900MHz, Duty Cycle = 10%

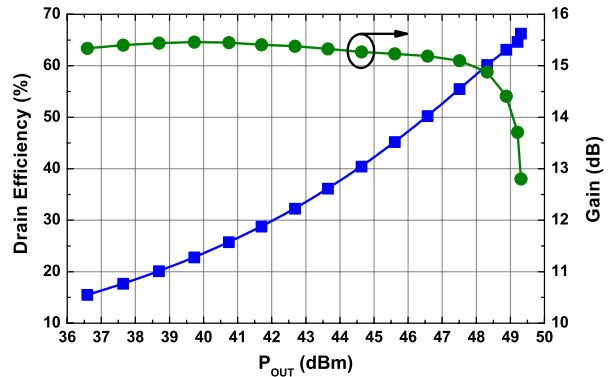


Figure 8 - Typical CW Performance at $V_{DS} = 20V$ Frequency = 900MHz

Nitronex Quadrature Combined Test Fixture

$V_{DS}=28V$, $I_{DQ}=1400mA$, $T_A=25^\circ C$ unless otherwise noted.

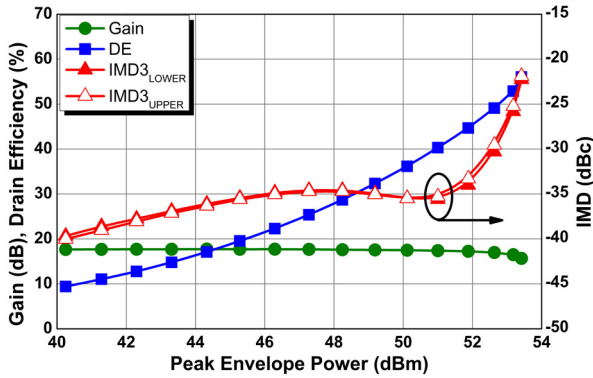


Figure 9 - Typical IMD3 Performance, Frequency = 900MHz, Tone spacing = 1MHz

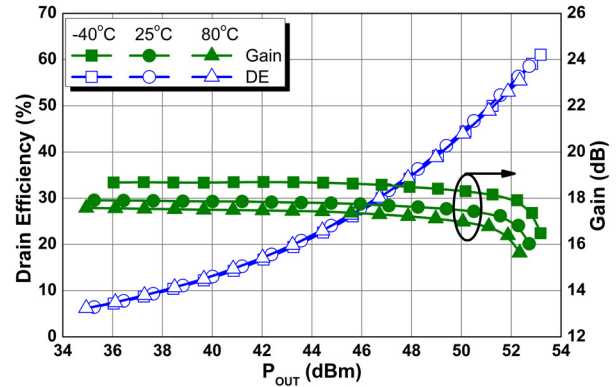


Figure 10 - Typical CW Performance over Temperature, Frequency = 900MHz

Typical Device Characteristics

$V_{DS}=28V$, $I_{DQ}=700mA$, One Single-Ended Transistor, $T_A=25^\circ C$ unless otherwise noted.

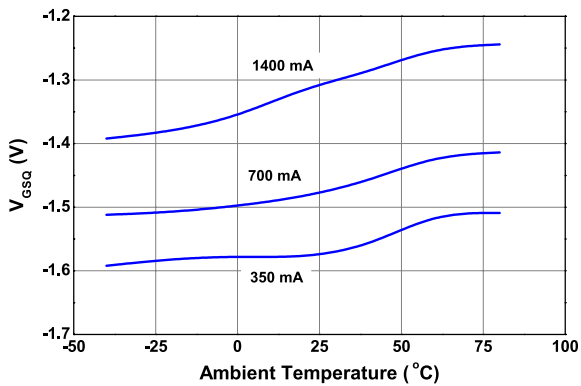


Figure 11 - Quiescent Gate Voltage (V_{GSQ}) Required to Reach I_{DQ} over Temperature

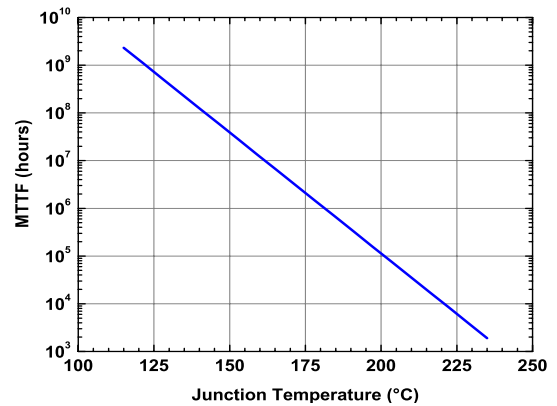


Figure 12 - MTTF of NRF1 devices as a function of junction temperature

Ordering Information¹

| Part Number | Description |
|-------------|---|
| NPT1007B | NPT1007 in AC780B-4 Metal-Ceramic Bolt-Down Package |

1: To find a Nitronex contact in your area, visit our website at <http://www.nitronex.com>

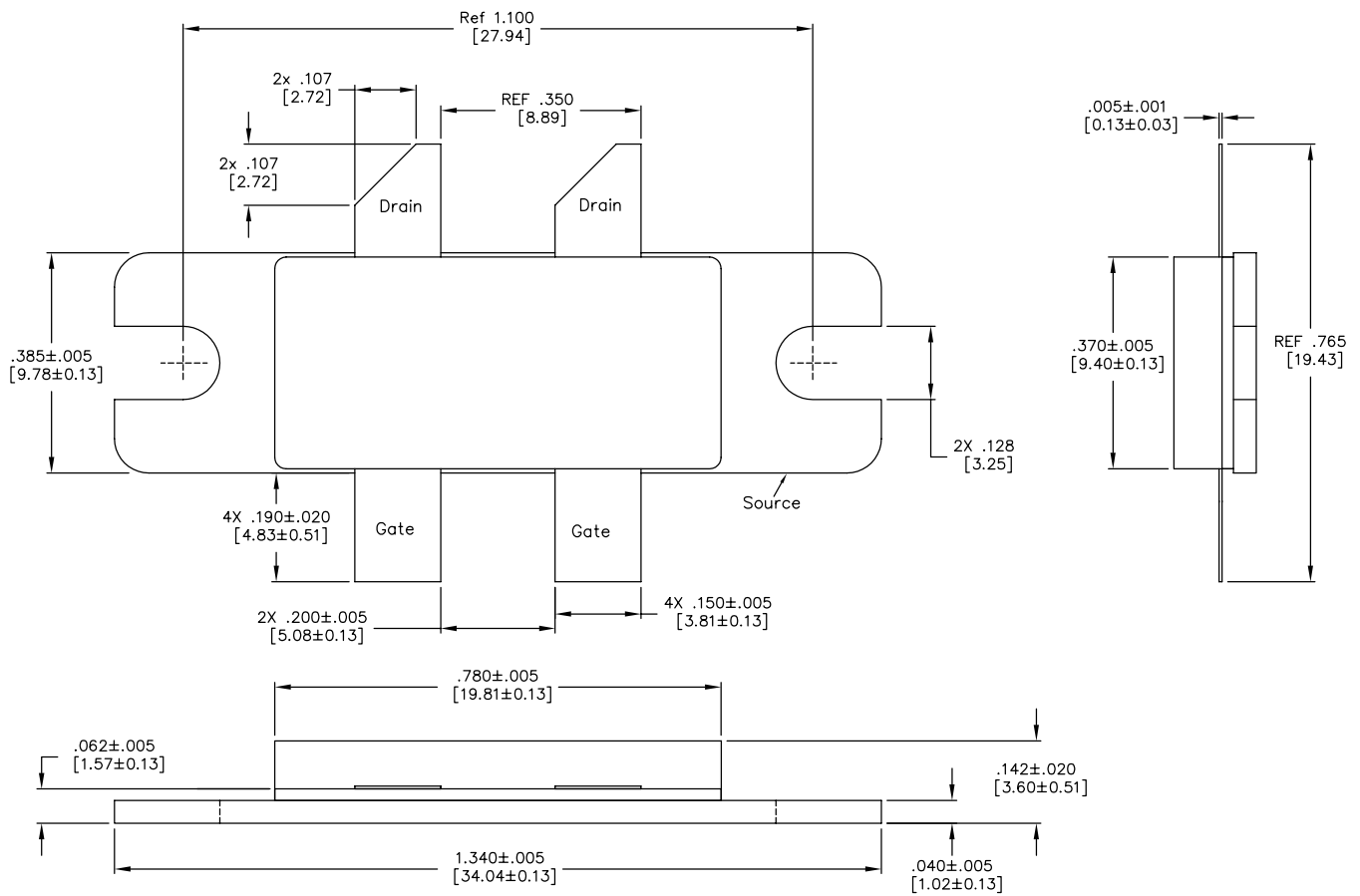


Figure 13 - AC780B-4 Metal-Ceramic Package Dimensions and Pinout (all dimensions are in inches [mm])

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Additional Information

**This part is lead-free and is compliant with the RoHS directive
(Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).**

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